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V1.0	

E3272s HiLink Firmware Release Notes

V1.0

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Revision Record

Date	Revision version	FW-WebUI/HiLink Version	Change Description	Author
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E3272s Firmware Release Notes V1.0

1 Main Features

The E3272s supports the following standards:

- LTE data service up to 130Mbit/s(Downlink) and 50Mbit/s(Uplink)
- DC-HSPA+ data service up to 43.2 Mbit/s
- HSPA+ data service up to 21.6 Mbit/s
- HSDPA packet data service of up to 14.4 Mbit/s
- HSUPA data service up to 5.76 Mbit/s
- WCDMA PS domain data service of up to 384 Kbit/s
- Equalizer and receive diversity
- microSD Card Slot (Up to 32G)
- Data and SMS Service
- HiLink features (Driverless, WEB UI, Auto connect)
- Plug and play
- Standard USB interface

2 Hardware

2.1 Hardware Specifications

Item	Specifications
Hardware Version	<ul style="list-style-type: none">● CH1E3272SM
Technical standard	<ul style="list-style-type: none">● LTE 3GPP R9● HSPA+/UMTS: 3GPP R99/R5/R6/R7/R8● GSM/GPRS/EDGE: 3GPP R99
External interfaces	USB: Type A with standard USB 2.0 High speed interface
	LED: indicating the status of the Data Card
	SD card: standard TF card interface
	SIM/USIM card: standard 6-pin SIM card interface
	RF interface: external RF interface
Maximum power consumption	≤ 3.5 W
Power supply	5V
Dimensions (D × W × H)	About 92mm(D) × 32mm(W) × 14mm (H)
Weight	≤ 50 g



Item	Specifications
Temperature	<ul style="list-style-type: none">Operating: -10°C to +40°CStorage: -20°C to +70°C
Humidity	5% to 95%
Base Information	<ul style="list-style-type: none">Plug and play (PnP)
	<ul style="list-style-type: none">Standard USB 2.0 High Speed interface, auto installation, convenient for use
Note: 3GPP = The 3rd Generation Partnership Project TS = Technical Specification LED = Light-Emitting Diode SIM = Subscriber Identity Module USIM = UMTS Subscriber Identity Module	

3 Firmware

3.1 Version Description

Firmware Version:	22.470.09.00.610
Baseline information	Balong V7R1 C35B270

3.2 Firmware Specifications

Firmware		
Item	Specifications	
Version	22.470.09.00.610	
Information	Platform	Balong V7R1
	Baseline	B270
	Feature	LTE Supported
Data service	GSM CS domain	<ul style="list-style-type: none">Uplink: 9.6/14.4 kbit/sDownlink: 9.6/14.4 kbit/s
	GPRS	<ul style="list-style-type: none">Uplink: 85.6 kbit/sDownlink: 85.6 kbit/s
	EDGE	<ul style="list-style-type: none">Uplink: 236.8 kbit/sDownlink: 236.8 kbit/s
	UMTS PS domain	<ul style="list-style-type: none">Uplink: 384 kbit/sDownlink: 384 kbit/s
	HSDPA	<ul style="list-style-type: none">14.4Mbit/s
	HSUPA	<ul style="list-style-type: none">5.76 Mbit/s



Firmware		
Item	Specifications	
	HSPA+	<ul style="list-style-type: none">• 21.6Mbit/s
	DC HSPA+	<ul style="list-style-type: none">• Uplink:5.76 Mbit/s• Downlink:43.2Mbit/s
	LTE	<ul style="list-style-type: none">• Uplink: 50Mbit/s• Downlink:130Mbit/s
SMS	<ul style="list-style-type: none">• SMS over SGs	
Operating System	<ul style="list-style-type: none">• Windows XP/Windows Vista/WIN 7/MAC/WIN8	

3.3 Improvement in the Previous Version

Index	Case ID	Issue Description

3.4 Known Limitations and Issues

Index	Case ID	Issue Description

4 WebUI/HiLink

4.1 Version Description

WebUI/HiLink Version: 13.100.11.00.610

4.2 WebUI/HiLink Specifications

Item	Specifications

4.3 Improvement in the Previous Version

Index	Case ID	Issue Description

4.4 Known Limitations and Issues

Index	Case ID	Issue Description